

# ANTREX Electronics

Electronic Components Sourcing Information

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## Product Reference Information

**Part Number:** B88069X1833T203  
**Manufacturer:** TDK  
**Package:** Tape & Reel (TR)  
**Availability:** Please confirm with sales

### Product Page:

<https://antrexco.com/product/details/tdk/b88069x1833t203.html>

### Request a Quote:

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## Contact Information

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CoC / RoHS / REACH documents available on request

Secure sourcing support for OEM / EMS projects

### Note:

This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.



## Surge arrester

### 3-electrode arrester

|                       |                        |
|-----------------------|------------------------|
| <b>Series/Type:</b>   | <b>TG30-A420XSMDs</b>  |
| <b>Ordering code:</b> | <b>B88069X1833T203</b> |
| Date:                 | 2019-08-05             |
| Version:              | 02                     |

## Product description

The TG30 series has been especially designed to meet data line protection requirements. The optimized design features a high level of protection against fast rising transients usually caused by lightning disturbances. For use in high frequency data-lines, the series offers ultra low capacitances and shows only marginally signal losses up to high frequencies. The devices are extremely reliable and are able to withstand high surge currents without destruction.

### Features

- Very small size
- Fast response time
- High current handling capability
- Stable performance over service life
- Ultra low capacitance and insertion loss
- High insulation resistance
- Excellent SMD handling
- RoHS-compatible

### Applications

#### Telecommunication:

- Ethernet, PoE, xDSL
- Cable modem, splitters, line cards
- Wireless-antenna protection

#### Others:

- CCTV
- ESD protection

## Product characteristics

|                                                                              |                                |                  |
|------------------------------------------------------------------------------|--------------------------------|------------------|
| Physical dimensions<br>(diameter × length)                                   | Ø0.13 × 0.26                   | in               |
|                                                                              | Ø3.5 × 6.8                     | mm               |
| Weight                                                                       | ~ 0.4                          | g                |
| Operating temperature                                                        | −40 ... +125                   | °C               |
| Recommended storage <sup>1)</sup><br>- temperature<br>- humidity<br>- period | +5 ... +35<br>45 ... 80<br>≤ 2 | °C<br>%<br>years |
| Climatic category (IEC 60068-1)                                              | 40/125/21                      |                  |
| Moisture sensitivity level <sup>2)</sup>                                     | 1                              |                  |
| Marking                                                                      | without                        |                  |

#### Notes:

<sup>1)</sup> Specified in terms of corrosion against Sn-plating

<sup>2)</sup> Tests according to JEDEC J-STD-020

**Surge arrester**
**B88069X1833T203**
**3-electrode arrester**
**TG30-A420XSMDs**
**Electrical specifications and stress test methods**

|                                                            |                                                                  |                |        |
|------------------------------------------------------------|------------------------------------------------------------------|----------------|--------|
| Nominal DC spark-over voltage <sup>3) 4) 5)</sup>          | 420                                                              | V              |        |
| Tolerance                                                  | ±30                                                              | %              |        |
| Min.                                                       | 294                                                              | V              |        |
| Max.                                                       | 546                                                              | V              |        |
| Impulse spark-over voltage <sup>5)</sup>                   |                                                                  |                |        |
| at 100 V/μs                                                | - for 99% of measured values<br>- typical values of distribution | < 700<br>< 600 | V<br>V |
| at 1 kV/μs                                                 | - for 99% of measured values<br>- typical values of distribution | < 800<br>< 700 | V<br>V |
| Service life                                               |                                                                  |                |        |
| 300 operations                                             | 8/20 μs <sup>7)</sup>                                            | 100            | A      |
| 10 operations [5× (+) & 5× (-)]                            | 8/20 μs <sup>6)</sup>                                            | 2              | kA     |
| 10 operations [5× (+) & 5× (-)]                            | 5/320 μs <sup>8) 9)</sup>                                        | 150            | A      |
| Insulation resistance at 100 V <sub>DC</sub> <sup>5)</sup> | > 1                                                              | GΩ             |        |
| Capacitance at 1 MHz <sup>5)</sup>                         | < 1                                                              | pF             |        |
| Arc voltage at 1 A                                         | ~ 20                                                             | V              |        |
| Glow to arc transition current                             | < 0.2                                                            | A              |        |
| Glow voltage                                               | ~ 150                                                            | V              |        |

<sup>3)</sup> At delivery AQL 0.65 level II, DIN ISO 2859

<sup>4)</sup> In ionized mode

<sup>5)</sup> Tip or ring electrode to center electrodes

<sup>6)</sup> Total current through center electrodes, half value through tip respectively ring electrode.

<sup>7)</sup> Tip to ring electrode

<sup>8)</sup> Tip to center electrode additional ring to center electrode

<sup>9)</sup> Test generator 6 kV, 10/700 μs, 40 Ω

Terms in accordance with ITU-T Rec. K.12 and IEC 61643-311.

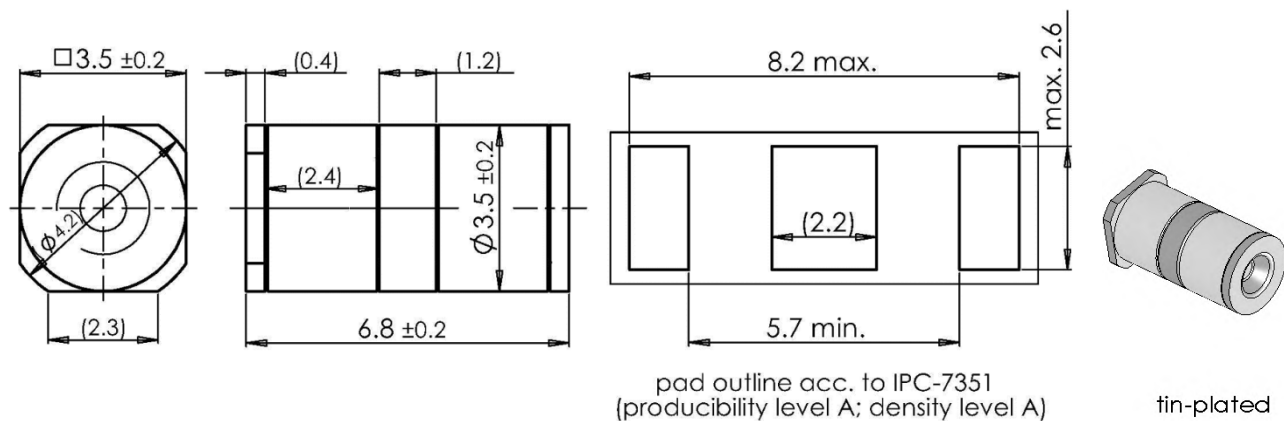
Surge arrester

B88069X1833T203

3-electrode arrester

TG30-A420XSMD5

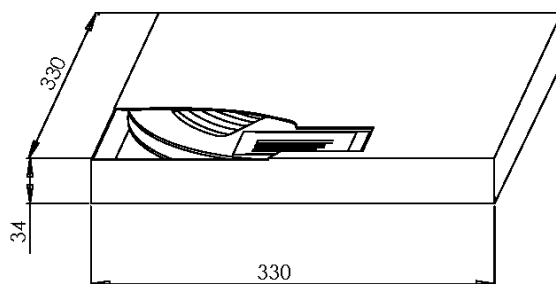
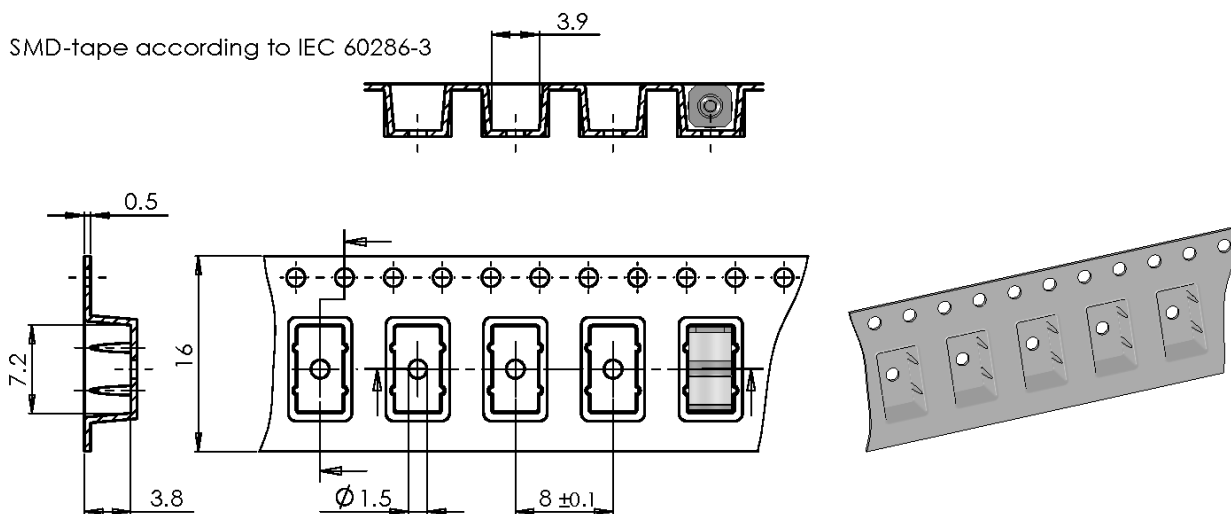
## Dimensional drawing in mm



## Ordering code and packing advice

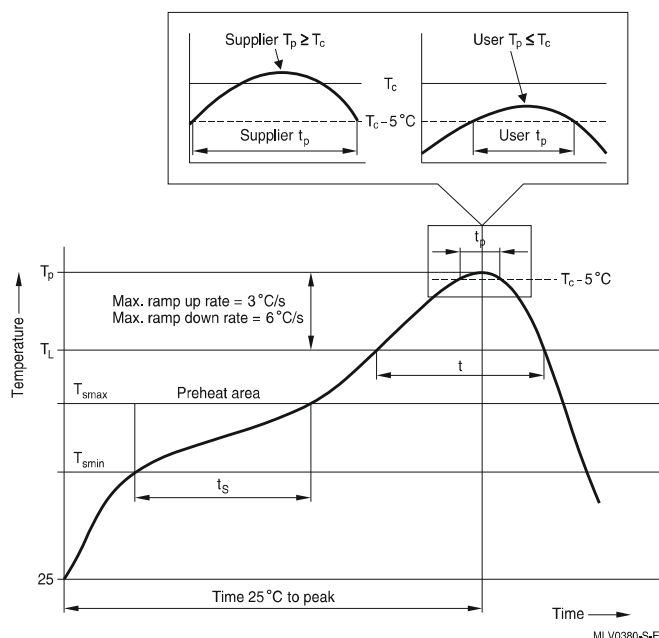
B88069X1833T203 = SMD-tape with 2000 pcs.

SMD-tape according to IEC 60286-3



## Soldering parameter

### Reflow soldering



| Reflow profile features                                                                                                                                                                                                                                                                |                                                      | Sn- Pb eutectic assembly         | Pb-free assembly                 |
|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------|----------------------------------|----------------------------------|
| Preheat and soak<br>- Temperature min<br>- Temperature max<br>- Time                                                                                                                                                                                                                   | $T_{smin}$<br>$T_{smax}$<br>$t_{smin}$ to $t_{smax}$ | 100 °C<br>150 °C<br>60 ... 120 s | 150 °C<br>200 °C<br>60 ... 180 s |
| Average ramp-up rate                                                                                                                                                                                                                                                                   | $T_{smax}$ to $T_p$                                  | max. 3 °C/ s                     | max. 3 °C/ s                     |
| Liquidous temperature<br>Time at liquidous                                                                                                                                                                                                                                             | $T_L$<br>$t_L$                                       | 183 °C<br>60 ... 150 s           | 217 °C<br>60 ... 150 s           |
| Peak package body temperature *,<br>Classification temperature **                                                                                                                                                                                                                      | $T_p$ , $T_c$                                        | 220 ... 235 °C **                | 245 ... 260 °C **                |
| Time ( $t_p$ ) ** within<br>5 °C of the specified<br>classification<br>temperature ( $T_c$ )                                                                                                                                                                                           |                                                      | 20 s ***                         | 30 s ***                         |
| Average ramp-down rate                                                                                                                                                                                                                                                                 | $T_p$ to $T_{smax}$                                  | max. 6 °C/ s                     | max. 6 °C/ s                     |
| Time 25 °C to peak temperature                                                                                                                                                                                                                                                         |                                                      | max. 6 min                       | max. 8 min                       |
| * = Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.<br>** = For details please refer to JEDEC J-STD-020D.<br>*** = Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum. |                                                      |                                  |                                  |

Surface mounted components (SMD) may exhibit a temporary increase in the DC spark-over voltage after the solder reflow process. The components will recover within 24 hours. There is no quality defect nor change in protection levels during the temporary change in DC spark-over voltage.

## Cautions and warnings

- Do not operate surge arresters in power supply networks, whose maximum operating voltage exceeds the minimum spark-over voltage of the surge arresters.
- Surge arresters may become hot in the event of longer periods of current stress (burn risk). In the event of overload the connectors may fail or the component may be destroyed.
- Surge arresters must be handled with care and must not be dropped.
- Do not continue to use damaged surge arresters.
- The shown SMD pad dimensions represent a safe way to mount the arrester and are a recommendation of the manufacturer. During the reflow process it must be assured that no solder material reduces the insulation distance between the pads below the arrester.
- SMD surge arresters should be soldered within 24 month after shipment.

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## Important notes

8. The trade names EPCOS, CeraCharge, CeraDiode, CeraLink, CeraPad, CeraPlas, CSMP, CTVS, DeltaCap, DigiSiMic, ExoCore, FilterCap, FormFit, LeaXield, MiniBlue, MiniCell, MKD, MKK, MotorCap, PCC, PhaseCap, PhaseCube, PhaseMod, PhiCap, PowerHap, PQSine, PQvar, SIFERRIT, SIFI, SIKOREL, SilverCap, SIMDAD, SiMic, SIMID, SineFormer, SIOV, ThermoFuse, WindCap are **trademarks registered or pending** in Europe and in other countries. Further information will be found on the Internet at [www.tdk-electronics.tdk.com/trademarks](http://www.tdk-electronics.tdk.com/trademarks).

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